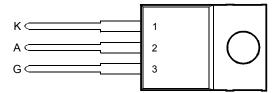
- 8 A Continuous On-State Current
- 80 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 20 mA

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
	TIC116D		400	
Repetitive peak off-state voltage	TIC116M	V	600	٧
	TIC116S	V_{DRM}	700	
	TIC116N		800	
	TIC116D		400	٧
Repetitive peak reverse voltage	TIC116M	V	600	
	TIC116S	V_{RRM}	700	
	TIC116N		800	
Continuous on-state current at (or below) 70°C case temperature (see Note 1)		I _{T(RMS)}	8	Α
Average on-state current (180° conduction angle) at (or below) 70°C case temperature			5	Α
(see Note 2)		I _{T(AV)}	3	
Surge on-state current at (or below) 25°C case temperature (see Note 3)		I _{TM}	80	Α
Peak positive gate current (pulse width ≤ 300 μs)		I _{GM}	3	Α
Peak gate power dissipation (pulse width ≤ 300 μs)		P_{GM}	5	W
Average gate power dissipation (see Note 4)		$P_{G(AV)}$	1	W
Operating case temperature range		T _C	-40 to +110	°C
Storage temperature range		T _{stg}	-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds		T_L	230	°C

- NOTES: 1. These values apply for continuous dc operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 2. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
 - 4. This value applies for a maximum averaging time of 20 ms.



TIC116 SERIES SILICON CONTROLLED RECTIFIERS

APRIL 1971 - REVISED JUNE 2000

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}		T _C = 110°C			2	mA
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			2	mA
I _{GT}	Gate trigger current	V _{AA} = 12 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		8	20	mA
V _{GT}	Gate trigger voltage	$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = - 40°C			2.5	
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$			0.8	1.5	٧
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = 110°C	0.2			
I _H	Holding current	V _{AA} = 12 V Initiating I _T = 100 mA		T _C = - 40°C			100	mA
		$V_{AA} = 12 \text{ V}$ Initiating $I_T = 100 \text{ mA}$					40	
V _T	On-state voltage	I _T = 8 A	(see Note 5)				1.7	>
dv/dt	Critical rate of rise of off-state voltage	V _D = rated V _D	I _G = 0	T _C = 110°C		400		V/µs

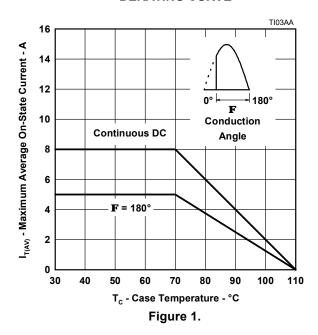
NOTE 5: This parameter must be measured using pulse techniques, t_p = 300 μs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

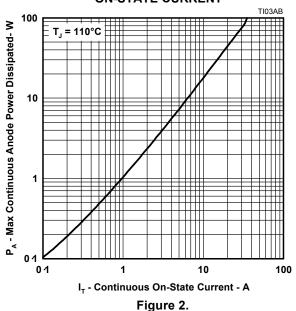
THERMAL INFORMATION

AVERAGE ON-STATE CURRENT DERATING CURVE



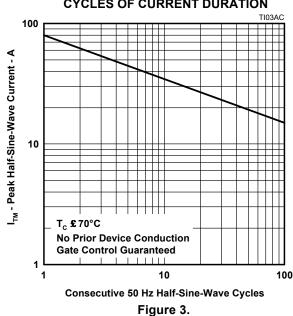
ON-STATE CURRENT

MAX ANODE POWER LOSS



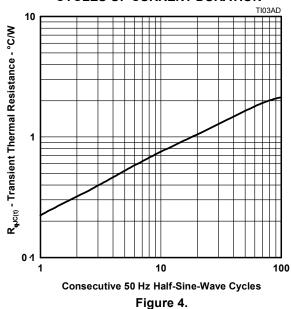
SURGE ON-STATE CURRENT

CYCLES OF CURRENT DURATION



TRANSIENT THERMAL RESISTANCE

CYCLES OF CURRENT DURATION

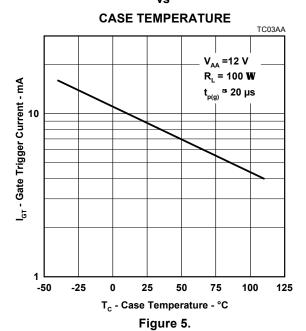


PRODUCT INFORMATION



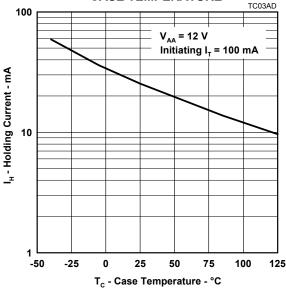
TYPICAL CHARACTERISTICS

GATE TRIGGER CURRENT vs

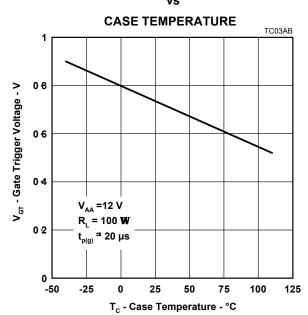


HOLDING CURRENT vs

CASE TEMPERATURE



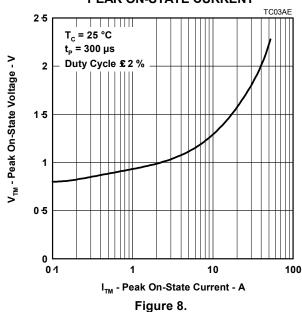
GATE TRIGGER VOLTAGE



PEAK ON-STATE VOLTAGE vs

Figure 6.

PEAK ON-STATE CURRENT



PRODUCT INFORMATION

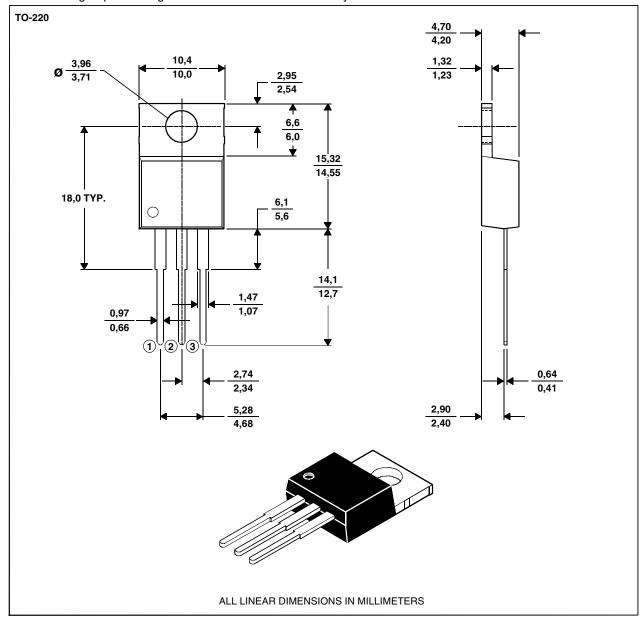
Figure 7.

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.



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